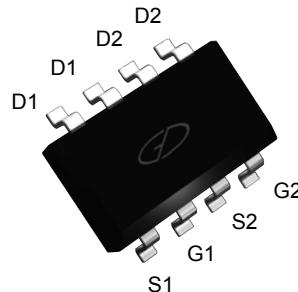
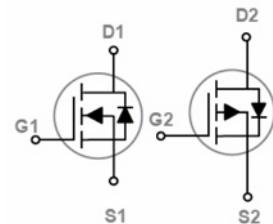


Main Product Characteristics

Channel	N-Channel	P-Channel
B_{VDSS}	30V	-30V
$R_{DS(ON)}$	20mΩ	50mΩ
I_D	8A	-5.5A



SOP-8



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The SSFQ3712 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating		Unit
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Drain Current – Continuous ($T_C=25^\circ\text{C}$)	I_D	8	-5.5	A
Drain Current – Continuous ($T_C=100^\circ\text{C}$)		5	-3.5	A
Drain Current – Pulsed ¹	I_{DM}	32	-22	A
Single Pulse Avalanche Energy ^{2,6}	E_{AS}	14	5	mJ
Single Pulse Avalanche Current ²	I_{AS}	17	10	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	2.5		W
Power Dissipation – Derate above 25°C		0.02		W/ $^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150		$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150		$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	R_{JA}	---	62.5	$^\circ\text{C/W}$
Thermal Resistance Junction to Case	R_{JC}	---	50	$^\circ\text{C/W}$

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	30	---	---	V
Drain-Source Leakage Current	I_{DSS}	$\text{V}_{\text{DS}}=30\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	±100	nA
On Characteristics						
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=8\text{A}$	---	15	20	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=5\text{A}$	---	21	30	$\text{m}\Omega$
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	1.5	2.5	V
$\text{V}_{\text{GS(th)}}$ Temperature Coefficient	$\Delta \text{V}_{\text{GS(th)}}$		---	-4	---	mV°C
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=3\text{A}$	---	3	---	S
Dynamic Characteristics						
Total Gate Charge ^{3,4}	Q_{g}	$\text{V}_{\text{DS}}=15\text{V}$, $\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=8\text{A}$	---	4.1	6	nC
Gate-Source Charge ^{3,4}	Q_{gs}		---	1	1.4	
Gate-Drain Charge ^{3,4}	Q_{gd}		---	2.1	4	
Turn-On Delay Time ^{3,4}	$\text{T}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=15\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=6\Omega$ $\text{I}_D=1\text{A}$	---	2.8	5	nS
Rise Time ^{3,4}	T_{r}		---	7.2	14	
Turn-Off Delay Time ^{3,4}	$\text{T}_{\text{d(off)}}$		---	15.8	30	
Fall Time ^{3,4}	T_{f}		---	4.6	9	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=25\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	345	500	pF
Output Capacitance	C_{oss}		---	55	80	
Reverse Transfer Capacitance	C_{rss}		---	32	55	
Gate Resistance	R_{g}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	3.2	6.4	Ω
Drain-Source Diode Characteristics						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_{s}	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	8	A
Pulsed Source Current	I_{SM}		---	---	16	A
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_{\text{s}}=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. $\text{V}_{\text{DD}}=25\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $\text{I}_{\text{AS}}=17\text{A}$, $\text{R}_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_\text{D}=-250\mu\text{A}$	-30	---	---	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $\text{I}_\text{D}=-1\text{mA}$	---	-0.03	---	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$\text{I}_{\text{DS}}^{\text{SS}}$	$\text{V}_{\text{DS}}=-30\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$\text{V}_{\text{DS}}=-24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
Gate-Source Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
On Characteristics						
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_\text{D}=-5\text{A}$	---	40	50	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_\text{D}=-3\text{A}$	---	65	90	$\text{m}\Omega$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_\text{D}=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
$\text{V}_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta \text{V}_{\text{GS}(\text{th})}$		---	4	---	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$\text{V}_{\text{DS}}=-10\text{V}$, $\text{I}_\text{D}=-3\text{A}$	---	3.5	---	S
Dynamic Characteristics						
Total Gate Charge ^{6, 7}	Q_g	$\text{V}_{\text{DS}}=-15\text{V}$, $\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_\text{D}=-3\text{A}$	---	5.1	7	nC
Gate-Source Charge ^{6, 7}	Q_{gs}		---	2	3	
Gate-Drain Charge ^{6, 7}	Q_{gd}		---	2.2	4	
Turn-On Delay Time ^{6, 7}	$\text{T}_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=-15\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{R}_\text{G}=6\Omega$ $\text{I}_\text{D}=-1\text{A}$	---	3.4	6	nS
Rise Time ^{6, 7}	T_r		---	10.8	21	
Turn-Off Delay Time ^{6, 7}	$\text{T}_{\text{d}(\text{off})}$		---	26.9	51	
Fall Time ^{6, 7}	T_f		---	6.9	13	
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=-15\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{F}=1\text{MHz}$	---	560	810	pF
Output Capacitance	C_{oss}		---	55	80	
Reverse Transfer Capacitance	C_{rss}		---	40	60	
Drain-Source Diode Characteristics						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	$\text{V}_\text{G}=\text{V}_\text{D}=0\text{V}$, Force Current	---	---	-5.5	A
Pulsed Source Current	I_{SM}		---	---	-11	A
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_\text{s}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note:

5. $\text{V}_{\text{DD}}=-25\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $\text{I}_{\text{AS}}=-10\text{A}$, $\text{R}_\text{G}=25\Omega$, Starting $T_J=25^\circ\text{C}$.
6. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$ duty cycle $\leq 2\%$.
7. Essentially independent of operating temperature.

N-Channel Typical Electrical and Thermal Characteristic Curves

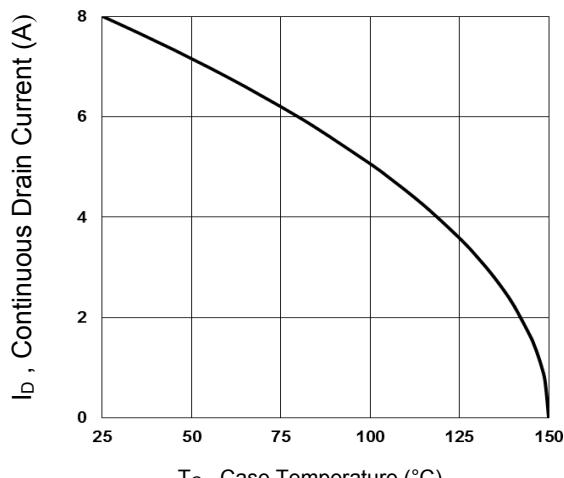


Fig.1 Continuous Drain Current vs. T_c

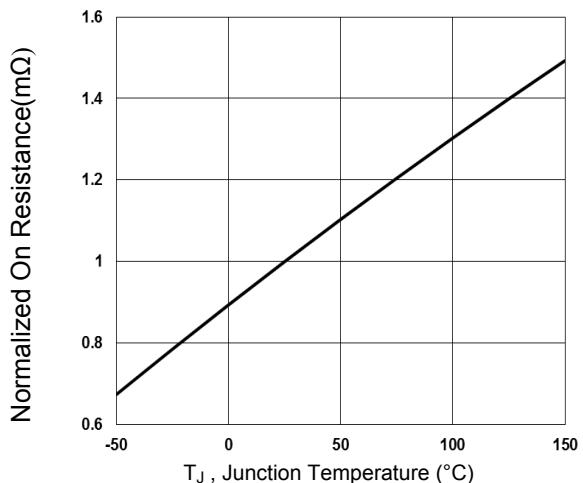


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

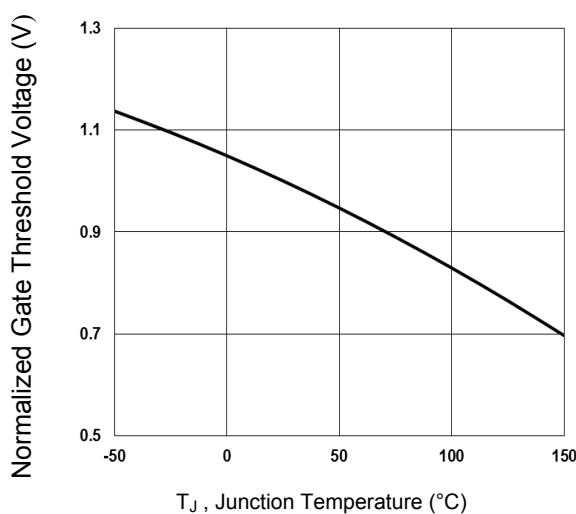


Fig.3 Normalized V_{th} vs. T_J

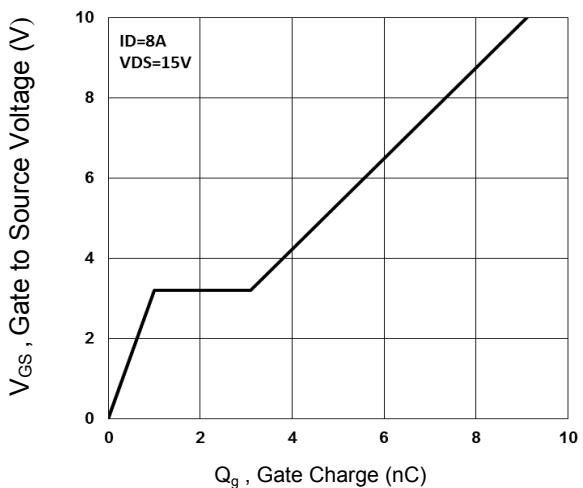


Fig.4 Gate Charge Characteristics

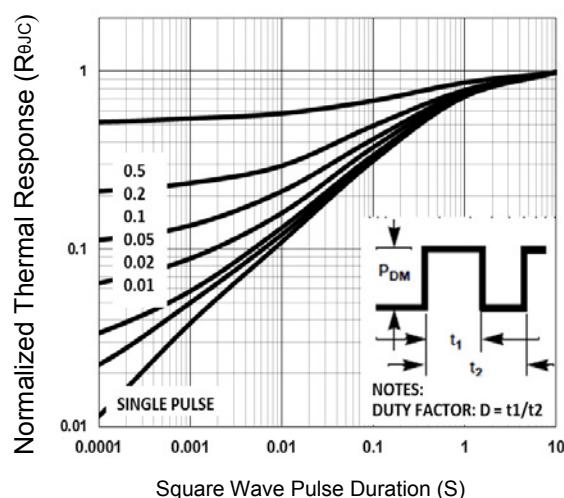


Fig.5 Normalized Transient Impedance

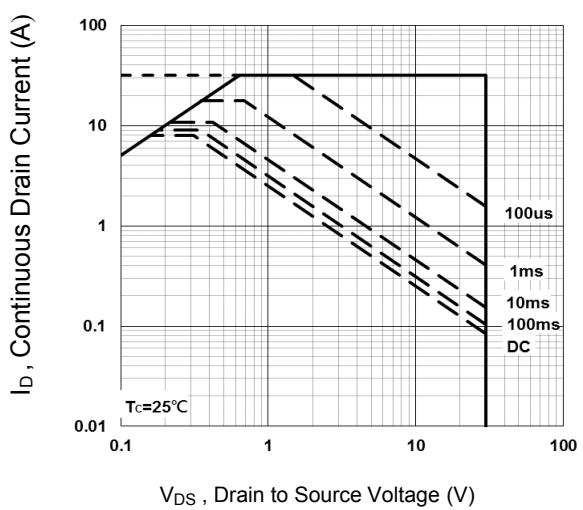


Fig.6 Maximum Safe Operation Area

P-Channel Typical Electrical and Thermal Characteristic Curves

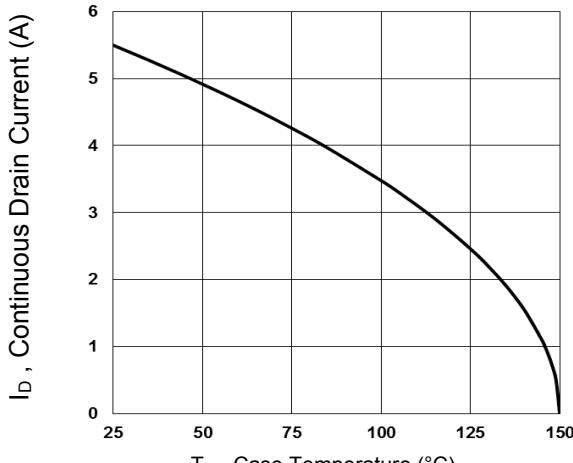


Fig.1 Continuous Drain Current vs. T_c

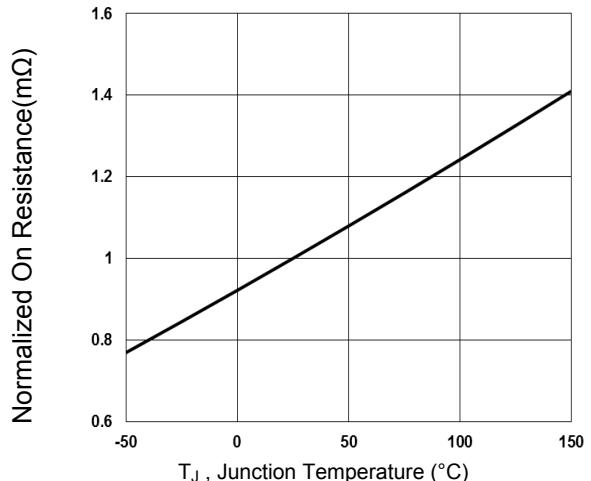


Fig.2 Normalized R_{DS(ON)} vs. T_J

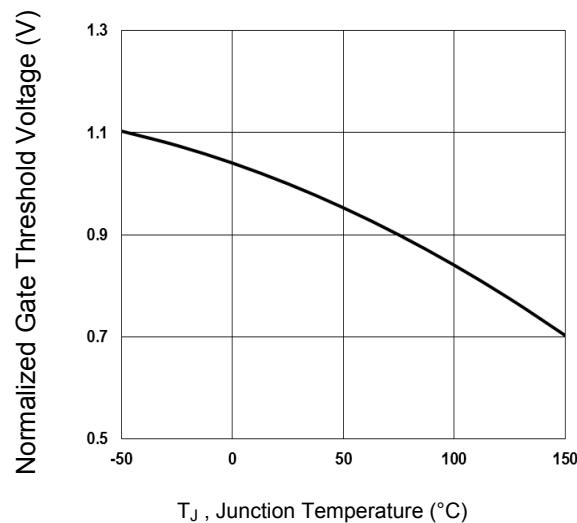


Fig.3 Normalized V_{th} vs. T_J

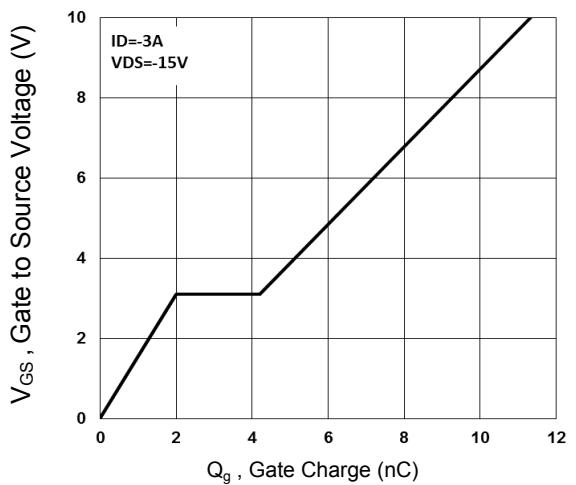


Fig.4 Gate Charge Characteristics

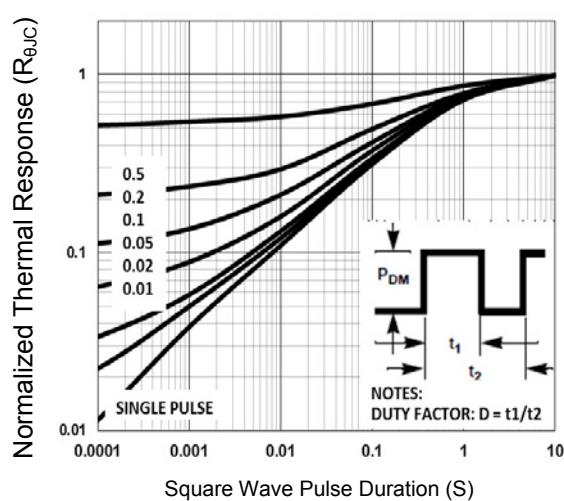


Fig.5 Normalized Transient Impedance

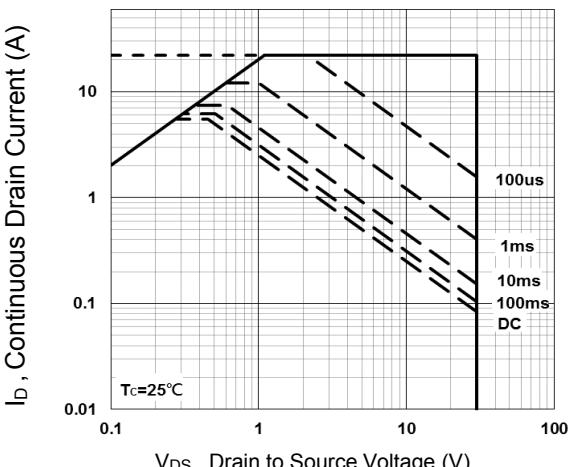
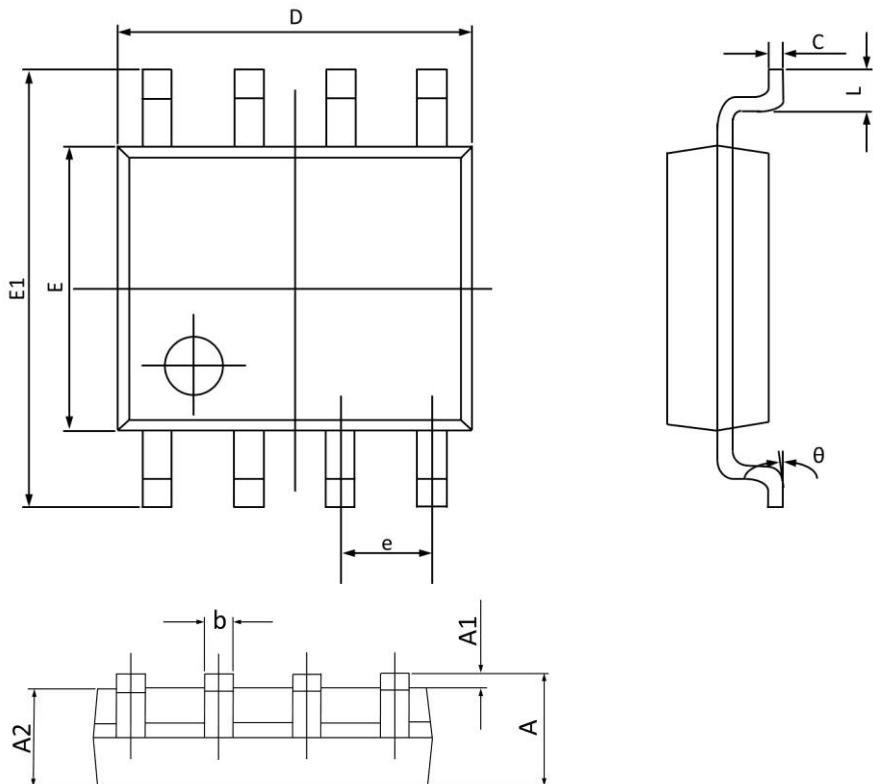


Fig.6 Maximum Safe Operation Area

Package Outline Dimensions

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.750	1.350	0.069	0.053
A1	0.250	0.100	0.010	0.004
A2	1.500	1.300	0.059	0.051
b	0.490	0.350	0.019	0.014
C	0.260	0.190	0.010	0.007
D	5.100	4.700	0.201	0.185
E	4.100	3.700	0.161	0.146
E1	6.200	5.800	0.244	0.228
e	1.27BSC		0.05BSC	
L	0.900	0.400	0.035	0.016
θ	8°	0°	8°	0°